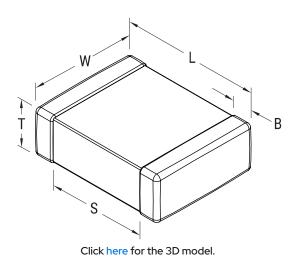


Specifications

Insulation Resistance



ESD SMD Comm COG, Ceramic, 0.047 uF, 2%, 25 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0.7 mm, 0805 / 2012



General Information	
Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	14 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
Т	1.25mm +/-0.15mm
S	0.7mm MIN
В	0.5mm +/-0.25mm
Case Code (EIA / mm)	0805 / 2012

Capacitance	0.047 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	2%
Voltage DC	25 VDC
ESD Level per AEC-Q200	25,000 V ESD Level
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Tomp Coefficient	000
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Capacitance Change with Reference to +25°C and 0 VDC	
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms

21.2766 GOhms

Packaging Specifications	
Packaging	Bulk, Bag
Packaging Quantity	1

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we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the	
requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us	
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